

# 1.5V Drive Pch MOSFET

## RZQ045P01

### ●Structure

Silicon P-channel MOSFET

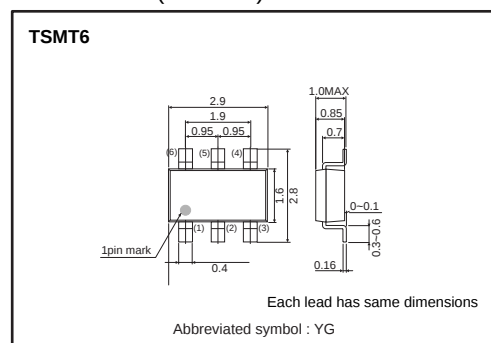
### ●Features

- 1) Low on-resistance.
- 2) High power package.
- 3) Low voltage drive. (1.5V)

### ●Applications

Switching

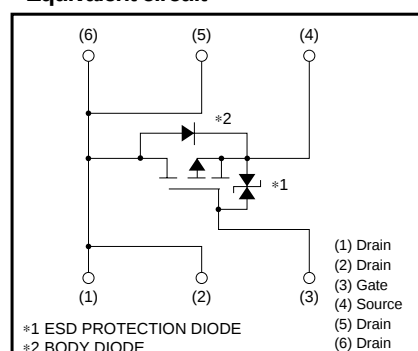
### ●Dimensions (Unit : mm)



### ●Packaging specifications

| Type      | Package                      | Taping |
|-----------|------------------------------|--------|
|           | Code                         | TR     |
|           | Basic ordering unit (pieces) | 3000   |
| RZQ045P01 |                              | ○      |

### ●Equivalent circuit



### ●Absolute maximum ratings (Ta=25°C)

| Parameter                    |            | Symbol      | Limits      | Unit |
|------------------------------|------------|-------------|-------------|------|
| Drain-source voltage         |            | $V_{DS}$    | -12         | V    |
| Gate-source voltage          |            | $V_{GS}$    | ±10         | V    |
| Drain current                | Continuous | $I_D$       | ±4.5        | A    |
|                              | Pulsed     | $I_{DP}$ *1 | ±12         | A    |
| Source current (Body diode)  | Continuous | $I_S$       | -1          | A    |
|                              | Pulsed     | $I_{SP}$ *1 | -12         | A    |
| Total power dissipation      |            | $P_D$ *2    | 1.25        | W    |
| Channel temperature          |            | $T_{ch}$    | 150         | °C   |
| Range of Storage temperature |            | $T_{stg}$   | -55 to +150 | °C   |

\*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$

\*2 Mounted on a ceramic board

### ●Thermal resistance

| Parameter          | Symbol           | Limits | Unit   |
|--------------------|------------------|--------|--------|
| Channel to ambient | $R_{th(ch-a)}$ * | 100    | °C / W |

\* Mounted on a ceramic board.

## Transistors

## ●Electrical characteristics (Ta=25°C)

| Parameter                               | Symbol         | Min. | Typ. | Max. | Unit | Conditions                         |
|-----------------------------------------|----------------|------|------|------|------|------------------------------------|
| Gate-source leakage                     | $I_{GSS}$      | —    | —    | ±10  | μA   | $V_{GS}=±10V$ , $V_{DS}=0V$        |
| Drain-source breakdown voltage          | $V_{(BR) DSS}$ | −12  | —    | —    | V    | $I_D = -1mA$ , $V_{GS}=0V$         |
| Zero gate voltage drain current         | $I_{DSS}$      | —    | —    | −1   | μA   | $V_{DS} = -12V$ , $V_{GS}=0V$      |
| Gate threshold voltage                  | $V_{GS(th)}$   | −0.3 | —    | −1.0 | V    | $V_{DS} = -6V$ , $I_D = -1mA$      |
| Static drain-source on-state resistance | $R_{DS(on)}$ * | —    | 25   | 35   | mΩ   | $I_D = -4.5A$ , $V_{GS} = -4.5V$   |
|                                         |                | —    | 31   | 43   | mΩ   | $I_D = -2.2A$ , $V_{GS} = -2.5V$   |
|                                         |                | —    | 39   | 58   | mΩ   | $I_D = -2.2A$ , $V_{GS} = -1.8V$   |
|                                         |                | —    | 50   | 100  | mΩ   | $I_D = -0.9A$ , $V_{GS} = -1.5V$   |
| Forward transfer admittance             | $ Y_{fs} $ *   | 6.5  | —    | —    | S    | $V_{DS} = -6V$ , $I_D = -4.5A$     |
| Input capacitance                       | $C_{iss}$      | —    | 2450 | —    | pF   | $V_{DS} = -6V$                     |
| Output capacitance                      | $C_{oss}$      | —    | 320  | —    | pF   | $V_{GS}=0V$                        |
| Reverse transfer capacitance            | $C_{rss}$      | —    | 290  | —    | pF   | $f=1MHz$                           |
| Turn-on delay time                      | $t_{d(on)}$ *  | —    | 12   | —    | ns   | $I_D = -2.2A$                      |
| Rise time                               | $t_r$ *        | —    | 75   | —    | ns   | $V_{DD} = -6V$<br>$V_{GS} = -4.5V$ |
| Turn-off delay time                     | $t_{d(off)}$ * | —    | 390  | —    | ns   | $R_L = 2.7Ω$                       |
| Fall time                               | $t_f$ *        | —    | 215  | —    | ns   | $R_G=10Ω$                          |
| Total gate charge                       | $Q_g$ *        | —    | 31   | —    | nC   | $V_{DD} = -6V$ $R_L = 1.3Ω$        |
| Gate-source charge                      | $Q_{gs}$ *     | —    | 4.5  | —    | nC   | $V_{GS} = -4.5V$ $R_G=10Ω$         |
| Gate-drain charge                       | $Q_{gd}$ *     | —    | 4.0  | —    | nC   | $I_D = -4.5A$                      |

\*Pulsed

## ●Body diode characteristics (Source-drain) (Ta=25°C)

| Parameter       | Symbol     | Min. | Typ. | Max. | Unit | Conditions                  |
|-----------------|------------|------|------|------|------|-----------------------------|
| Forward voltage | $V_{SD}$ * | —    | —    | −1.2 | V    | $I_S = -4.5A$ , $V_{GS}=0V$ |

\*Pulsed

## Transistors

## ●Electrical characteristic curves

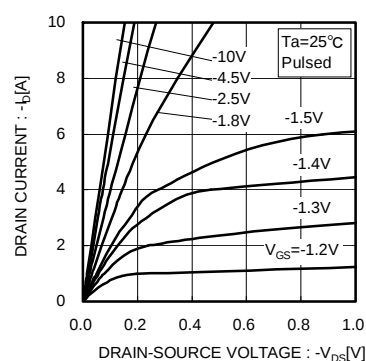


Fig.1 Typical Output Characteristics(I)

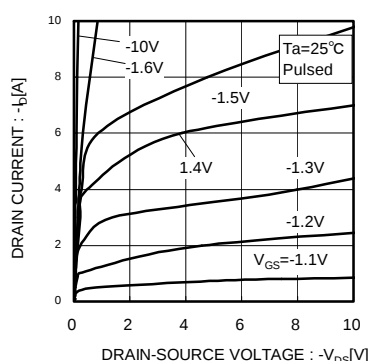


Fig.2 Typical Output Characteristics(II)

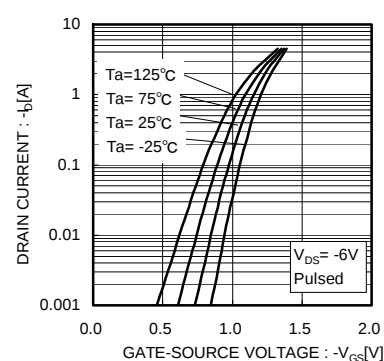


Fig.3 Typical Transfer Characteristics

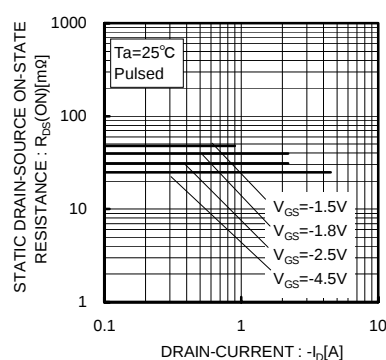


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

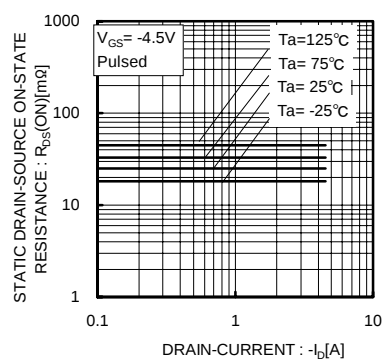


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

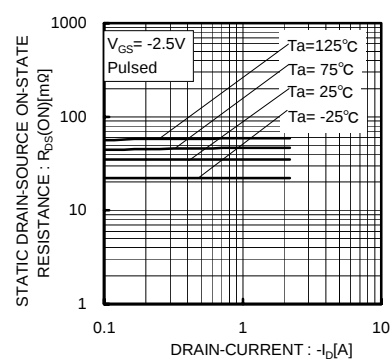


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(III)

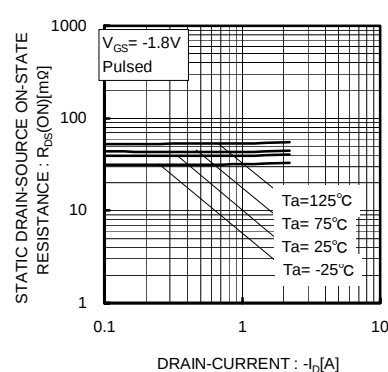


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(IV)

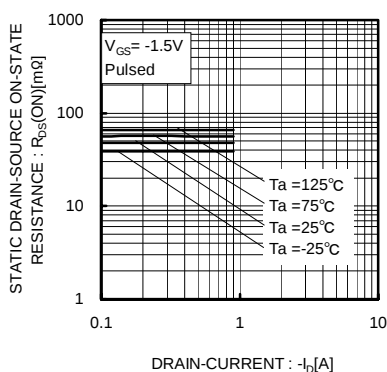


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(V)

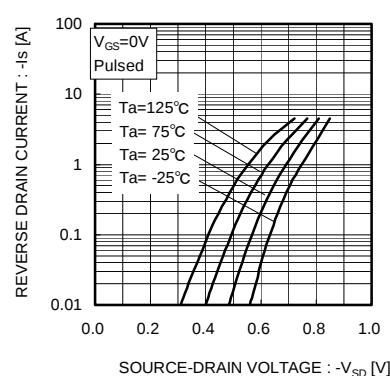


Fig.9 Reverse Drain Current vs. Source-Drain Voltage

## Transistors

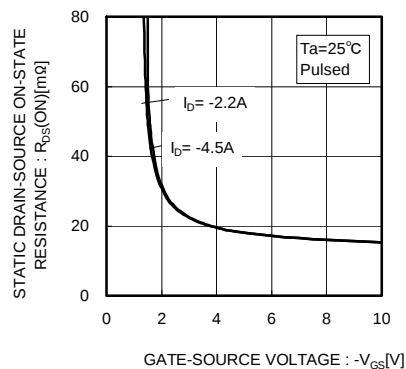


Fig.10 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

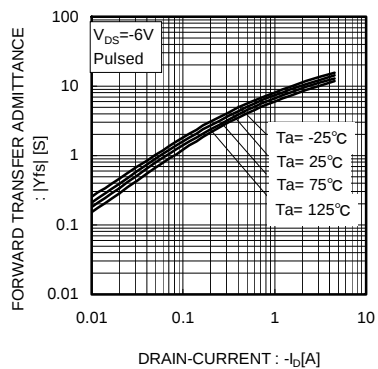


Fig.11 Forward Transfer Admittance vs. Drain Current

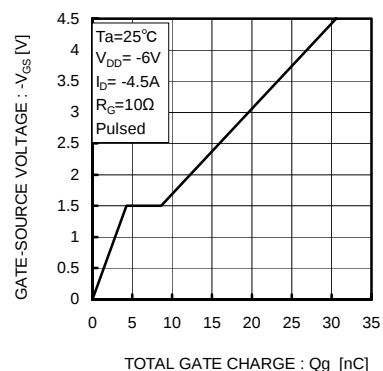


Fig.12 Dynamic Input Characteristics

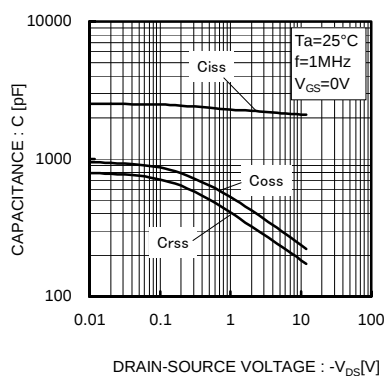


Fig.13 Typical Capacitance vs. Drain-Source Voltage

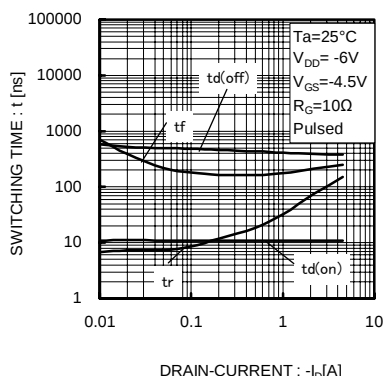


Fig.14 Switching Characteristics

## Transistors

### ●Measurement circuits

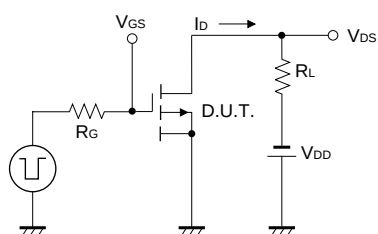


Fig.15 Switching Time Measurement Circuit

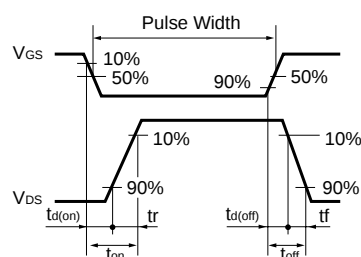


Fig.16 Switching Waveforms

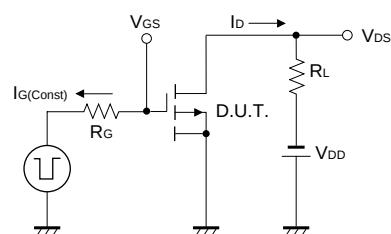


Fig.17 Gate Charge Measurement Circuit

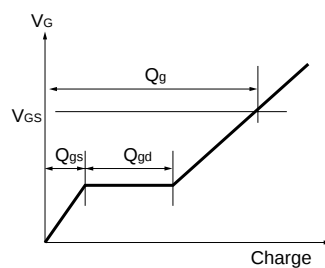


Fig.18 Gate Charge Waveform

### ●Notice

This product might cause chip aging and breakdown under the large electrified environment .  
Please consider to design ESD protection circuit.

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